

KB-1150 (ANSI : XPC/JIS:PP7)

覆铜箔酚醛树脂纸基层压板

特点

Features

- 成本低而使用范围广
- 弯曲度、扭曲度小且稳定
- 适合之冲孔温度为 40~70℃
- Low cost but with wide range of applications
- Warpage and twist are small and stable
- Suitable for punching at 40~70℃

General Properties 一般特性

Test Item 测试项目	Unit 单位	Test Condition 处理条件	Testing Method 测试方法	Specification 规格值	Typical Value 典型值
Solder Resistance (260℃) 耐浸焊性	Sec	A	JIS C 6481	≥10	15~30
Heat Resistance 耐热性	—	130℃ 30min	JIS C 6481	No Change 无异常	No Change 无异常
Peel Strength (Copper Foil 35μm) 铜箔剥离强度 (35μm 铜箔)	Kgf/cm	A 260℃/10Sec	JIS C 6481	≥1.2	1.7~1.9 1.7~1.9
Flexural Strength 屈曲强度	Lengthwise 纵向	A	JIS C 6481	≥8	14~16 13~14
	Crosswise 横向				
Volume Resistivity 体积阻抗系数	Ω-cm	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	5×10 ⁹ 5×10 ⁸	1×10 ¹² ~10 ¹³ 1×10 ¹⁰ ~10 ¹¹
Surface Resistivity 表面抗阻	Adhesive Side 粘接剂面	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	1×10 ¹⁰ 1×10 ⁹	1×10 ¹¹ ~10 ¹² 1×10 ¹⁰ ~10 ¹¹
	Laminate Side 积层板面	C-96/20/65 C-96/20/65+C-96/40/90		1×10 ⁹ 1×10 ⁷	1×10 ¹⁰ ~10 ¹¹ 1×10 ⁹ ~10 ¹⁰
Insulation Resistance 绝缘抗阻	Ω	C-96/20/65 C-96/20/65+D-2/100	JIS C 6481	1×10 ⁹ 1×10 ⁶	1×10 ¹⁰ ~10 ¹¹ 1×10 ⁷ ~10 ⁸
Chemical Resistance 耐化学性	—	3% NaOH 40℃ 3min 3%氢氧化钠 40℃3 分钟	JIS C 6481	No change 无异常	No change 无异常
		Boiled in trichloroethylene for 3 min 三氯乙烯中煮沸 3 分钟		No change 无异常	No change 无异常
Moisture Absorption 吸水率	%	E-24/50+D-24/23	JIS C 6481	≤2	1.0~1.5
Flammability 阻燃性	Rating	A	UL94	UL94 HB	HB
Dielectric Constant (1 MHz) 介电常数 (1 MHz)	—	C-96/20/65	JIS C 6481	≤5.5	4.0~5.0
		C-96/20/65+D-24/23		≤6.0	4.5~5.5
Dissipation Factor 介质损耗因子	—	C-96/20/65	JIS C 6481	≤0.05	0.025~0.035
		C-96/20/65-D-24/23		≤0.1	0.035~0.045
CTI Value CTI 值	V	0.1% NH ₄ CL	IEC 112	≥150	150 - 175
Punching Temperature 冲孔温度	℃	A	GB/T4722	40 - 70	40 - 70

Remarks: Typical values for reference only 注: 典型值只作参考 Stand values according to JIS-C-6485 规格值参照 JIS-C-6485

A = Keep the specimen originally without any process 保持原样, 不作处理

C = Temperature and humidity conditioning 在恒温恒湿的空气中处理

D = Immersing in distilled water with temperature control. 浸在恒温的水中处理

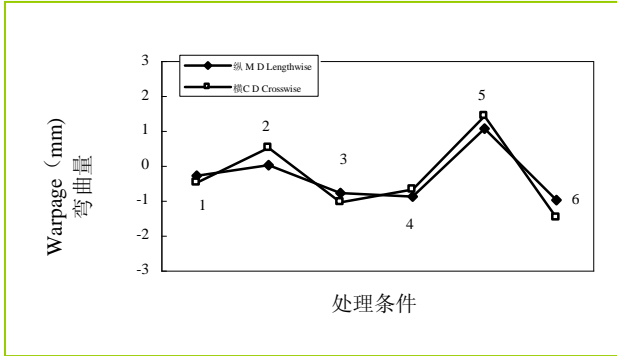
E = Temperature conditioning 在恒温的空气中处理

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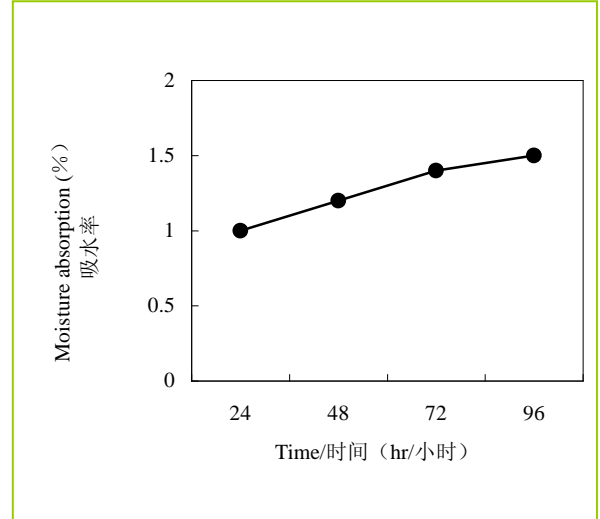
Speciality Chart 板材特性图

Warpage of PCB during processing/印制电路板
加工时弯曲度(Thickness 1.6mm single side)

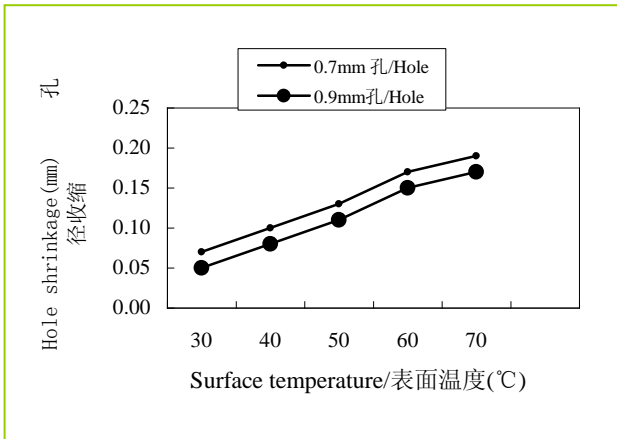


1. Feeding 投料	2. Heating at 130°C for 90 sec 130°C下加热 90 秒	3. Etching, Rinsing. Drying 蚀刻, 清洗, 烘干
4. Heating at 200°C for 30 sec 200°C下加热 30 秒	5. Punching at 50°C 50°C下冲孔	6. Soldering at 260°C for 5 sec 260°C 焊锡 5 秒

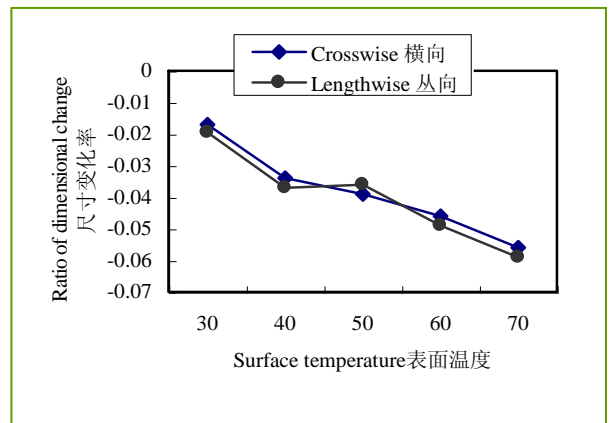
Moisture absorption 吸水率



Punched hole shrinkage
冲孔后孔径收缩



Dimensional change of punched PCB
冲孔后之尺寸变化



Purchasing Information 采购信息

Type 类型	Thickness 厚度	Copper Cladding 铜箔厚度	Regular Size (mm) 常规尺寸	CTI Value CTI 值
KB-1150 (HB 非阻燃纸板)	0.8mm ~ 1.6mm	35μm 70μm	1020*1020mm (40"* 40") 1020*1220mm (40"*48")	150V

Note: 1) Other sheet size and thickness could be available upon request. 可根据客户要求提供其它尺寸和厚度;

2) Speciality chart for reference only. 以上图表仅供参考;

3) Version updates without notice. 版本更新恕不另行通知。